# 2SB1154

## Silicon PNP epitaxial planar type

For power switching Complementary to 2SD1705

### ■ Features

- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Satisfactory linearity of forward current transfer ratio h<sub>FE</sub>
- Large collector current I<sub>C</sub>
- Full-pack package which can be installed to the heat sink with one screw

## ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-130	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-80	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	<del>-7</del>	V	
Collector current	$I_C$	-10	A	
Peak collector current	I <sub>CP</sub>	-20	A	
Collector power dissipation	P <sub>C</sub>	70	W	
$T_a = 25$ °C		3		
Junction temperature	Tj	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	

# Unit: mm 15.0±0.3 11.0±0.2 \$\frac{1}{2} \times \frac{1}{2} \times

## ■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = 0$	-80			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{\rm CB} = -100  V_{\rm c}  I_{\rm E} = 0$			-10	μΑ
Emitter-base cutoff current (Collector open)	$I_{\mathrm{EBO}}$	$V_{EB} = -5V, I_C = 0$			-50	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = -2 \text{ V}, I_0 = -0.1 \text{ A}$	45			_
	h <sub>FE2</sub> *	$V_{CE} = -2 \text{ V}, I_{C} = -3 \text{ A}$	60		260	
	h <sub>FE3</sub>	$V_{CE} = -2 \text{ V}, I_C = -6 \text{ A}$	30			
Collector-emitter saturation voltage	VCE(sat)1	$I_C = -6 \text{ A}, I_B = -0.3 \text{ A}$			- 0.5	V
	V <sub>CE(sat)2</sub>	$I_C = -10 \text{ A}, I_B = -1 \text{ A}$			-1.5	
Base-emitter saturation voltage	V <sub>BE(sat)1</sub>	$I_C = -6 \text{ A}, I_B = -0.3 \text{ A}$			-1.5	V
	V <sub>BE(sat)2</sub>	$I_C = -10 \text{ A}, I_B = -1 \text{ A}$			-2.5	
Transition frequency	$f_T$	$V_{CE} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = -6 \text{ A}, I_{B1} = -0.6 \text{ A}, I_{B2} = 0.6 \text{ A}$		0.5		μs
Storage time	t <sub>stg</sub>	$V_{CC} = -50 \text{ V}$		1.0		μs
Fall time	t <sub>f</sub>			0.2		μs

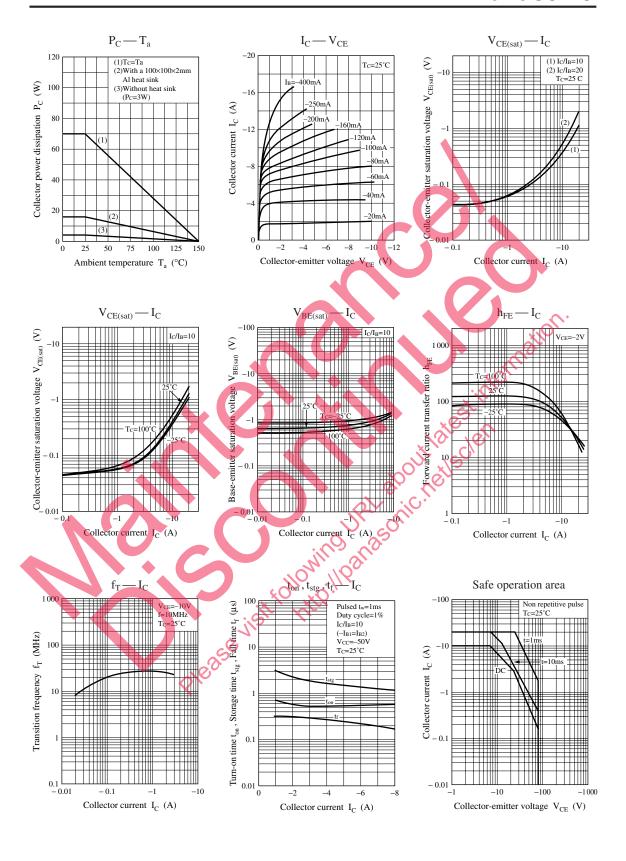
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

## 2. \*: Rank classification

Rank	R	Q	Р
h <sub>FE2</sub>	60 to 120	90 to 180	130 to 260

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# **Panasonic**



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